CLAIMS

What is claimed is:

1. An interconnect hub comprising:

a first side;

a second side opposite the first side to couple with the three or more dies, and wherein the second side includes a plurality of electrical couplings to electrically couple at least one of the three or more dies to another of the three or more dies; and

wherein the electrical couplings are to facilitate data transfer between at least a subset of the three or more dies;

wherein a corner of the second side of the interconnect hub is to physically couple with a corner of the three or more dies;

wherein the three or more dies are tiled dies; and

wherein the interconnect hub is positioned between the tiled dies and the substrate.

~~2. The interconnect hub of claim 1, wherein the second side is to physically couple with the three or more dies.~~

~~3. The interconnect hub of claim 1, wherein a corner of the second side of the interconnect hub is to physically couple with a corner of one of the three or more dies.~~

~~4. The interconnect hub of claim 1, wherein the three or more dies are tiled dies.~~

~~5.~~2. The interconnect hub of claim 1, wherein a subset of the plurality of electrical couplings are coupled with routing channels to facilitate direct communication between a first of the three or more dies and a second of the three or more dies.

~~6.~~3. The interconnect hub of claim 1 or claim 2, wherein the interconnect hub is a silicon bridge or interposer.

~~7.~~4. The interconnect hub of any one of claims 1 to 3, wherein the three or more dies are a same die rotated 90, 180, or 270 degrees.

~~8.~~5. The interconnect hub of any one of claims 1 to 4, wherein the interconnect hub includes at least one active component or at least one passive component.

~~9.~~6. The interconnect hub of any one of claims 1 to 5, wherein data transfer includes high-speed IO data transfer.

~~10.~~7. A system comprising:

a substrate;

three or more dies; and

an interconnect hub physically coupled to the three or more dies~~-~~, the interconnect hub comprising~~that includes~~:

a first side;

a second side opposite the first side to couple with the three or more dies, and wherein the second side includes a plurality of electrical couplings to electrically couple at least one of the three or more dies to another of the three or more dies; ~~and~~

wherein the electrical couplings are to facilitate ~~high-speed~~ data transfer between at least a subset of the three or more dies;

wherein a corner of the second side of the interconnect hub is to physically couple with a corner of the three or more die;

wherein the three or more dies are tiled dies; and

wherein the interconnect hub is positioned between the titled dies and the substrate.

~~11. The system of claim 10, wherein a corner of the second side of the interconnect hub is to physically couple with a corner of the three or more dies.~~

~~12. The system of claim 11, wherein the three or more dies are tiled dies.~~

~~13.~~8. The system of claim 10, wherein a subset of the plurality of electrical couplings are coupled with routing channels to facilitate direct communication between a first of the three or more dies and a second of the three or more dies.

~~14. The system of claim 10, wherein the three or more dies are a same die rotated 90, 180, or 270 degrees.~~

~~15.~~9. The system of claim 10 or claim 11, wherein the interconnect hub ~~includes at least one active component or at least one passive component~~is a silicon bridge or interposer.

10. The system of any one of claims 10 to 12, wherein the three or more dies are a same die rotated 90, 180, or 270 degrees.

~~16.~~11. The system of any one of claims 10 to 13, wherein the ~~second side of the~~ interconnect hub ~~is directly coupled with an~~includes at least one active component or at least one passive component.~~side of the three or more dies.~~

~~17.~~12. The system of any one of claims 10 to 14, wherein data transfer includes high-speed IO data transfer.

~~18.~~13. A method comprising:

positioning three or more dies in a tiled formation within a plane; and

electrically coupling a side of an interconnect hub to a side of the three or more dies, wherein the plane of the interconnect hub is substantially parallel to the plane of the dies in the tiled formation to facilitate high-speed data transfer between the dies;

wherein electrically coupling further includes physical coupling to a corner of each of the three or more dies; and

wherein the interconnect hub is between the dies in the tiled formation and a substrate.

~~19. The method of claim 18, wherein electrically coupling further includes physical coupling to a corner of each of the three or more dies.~~

~~20.~~14. The method of claim ~~19~~13, wherein electrically coupling the side of the interconnect hub to a side of the three or more dies further includes electrically coupling the side of the interconnect hub to an active side of the three or more dies.